



DC - 30.0 GHz.

Model: CVDT-XXXX-C-50

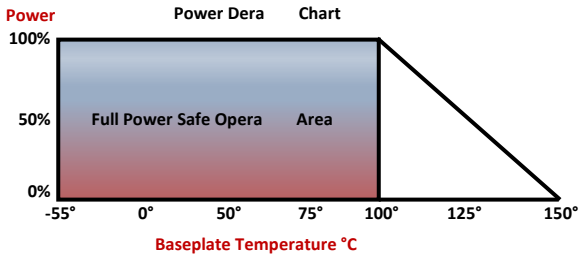
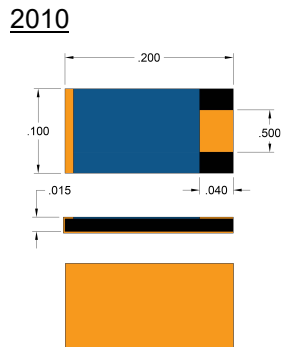
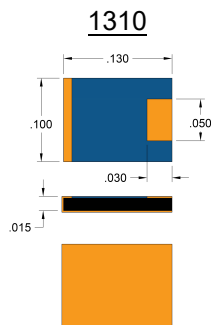
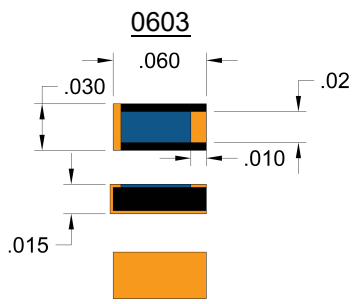
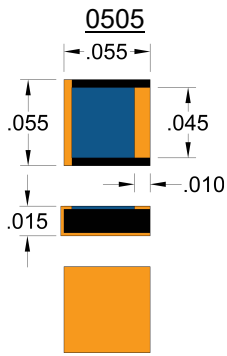
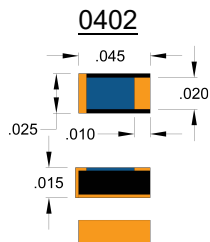
Chip Configurations

0402, 0505, 0603, 1310, 2010



DIA-FILM Chip Terminations are manufactured using CVD Diamond substrate material which has the highest thermal conductivity of any material known to man for use with electronic components. These termination chips are offered in various standard sizes having the capability of dissipating 20 - 200 watts of CW power and operate from -65° C to +150°C. With a low dielectric constant CVD Diamond is an excellent choice for high frequency design. The resistor structure is all thin-film utilizing the latest thin-film processing and pure metals. The resistor material is self-passivating Tantalum/Nitride combined with Titanium/Tungsten, Palladium, nickel and Gold films which produces these high reliability components. These terminations are designed for Gold/Tin, Gold/Germanium and Soft-Solder attachment. Silver epoxy can be used but not recommended for power dissipation over 1 watt. They can be delivered in Gel-Pak, Waffle packaging bulk or tape and reel. Please contact the factory for any special requirements or packaging. Tape and reel is standard packaging. All chips are RoHS compliant and are designed to meet MIL-PRF-55342.

CVD DIAMOND TERMINATION CHIP SELECTION CHART				
Part Number	Resistance (Ω) ±5%	Frequency Range	Power (Watts)	VSWR (Max)
CVDT-0402-C-50	50.0	DC - 8 GHz	10	1.6:1
CVDT-0505-C-50	50.0	DC - 20 GHz	50	1.6:1
CVDT-0603-C-50	50.0	DC - 28 GHz	50	1.6:1
CVDT-1310-C-50	50.0	DC - 14 GHz	150	1.6:1
CVDT-2010-C-50	50.0	DC - 12 GHz	200	1.6:1



Part Number Example:

